



# 100% Material Declaration Data Sheet CS324

PK480 (v1.0) June 17, 2011

**Average Weight: 0.545 g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
<b>Silicon Die</b>					<b>0.009997</b>	<b>1.834</b>
	Silicon	7440-21-3	100.00	Main material	0.009997	
<b>Die Attach Material</b>					<b>0.007051</b>	<b>1.294</b>
	Silver	7440-22-4	77.50	Main material	0.005465	
	Bismaleimide monomer	Trade Secret	15.00	Main material	0.001058	
	Acrylate monomer	Trade Secret	7.50	Main material	0.000529	
<b>Gold Wire</b>					<b>0.006702</b>	<b>1.230</b>
	Gold	7440-57-5	99.05	Main material	0.006638	
	Palladium	7440-05-3	0.95	Dopant	0.000064	
<b>Mold Compound</b>					<b>0.216990</b>	<b>39.815</b>
	Solid Epoxy Resin	Trade Secret	5.00	Main material	0.010850	
	Phenol Resin	Trade Secret	5.00	Main material	0.010850	
	Fused Silica	60676-86-0	84.45	Filler	0.183248	
	Metal Hydroxide	Trade Secret	5.00	Flame retardant	0.010850	
	Carbon Black	1333-86-4	0.55	Color agent	0.001193	
<b>Solder Balls</b>					<b>0.096708</b>	<b>17.745</b>
	Tin (Sn)	7440-31-5	63.00	Main material	0.060926	
	Lead (Pb)	7439-92-1	37.00	Main material	0.035782	
<b>Substrate</b>					<b>0.207552</b>	<b>38.083</b>
	Copper (Cu)	7440-50-8	13.309	Main material	0.027623	
	Nickel (Ni)	7440-02-0	4.696	Main material	0.009747	
	Gold (Au)	7440-57-5	5.606	Main material	0.011635	
	Glass fiber	65997-17-3	19.884	Glass fiber	0.041270	
	Non-Halogen Fire retardant	NA	0.082	Flame retardant	0.000170	
	BT (core)	NA	43.154	Core	0.089567	
	Solder mask	NA	13.269	Solder mask	0.027540	

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## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
6/17/11	1.0	Initial Xilinx release.

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